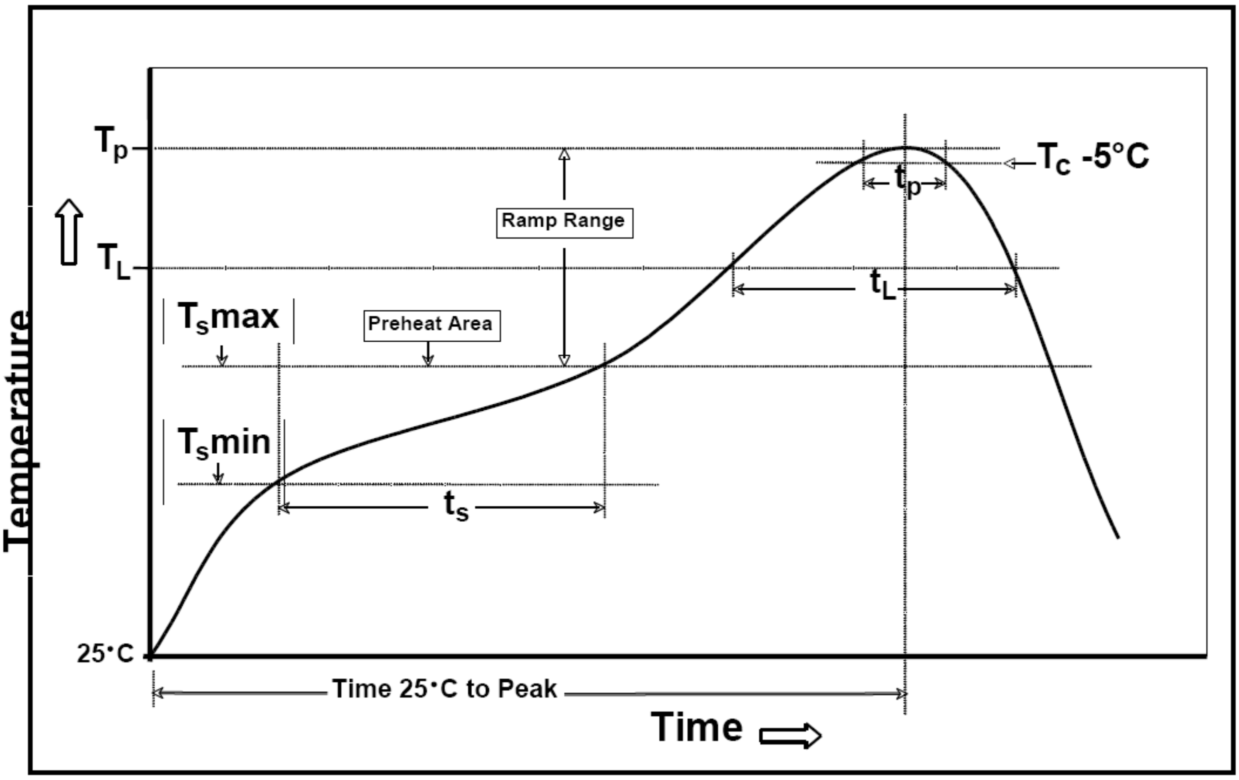
Solder profile for lead free reflow process

Figure 1 Classification Reflow Profile for SMT components



refer to IPC/JEDEC J-STD-020D

Table 1 Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Ts_{max} to Tp)	3℃/second max.
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (ts_{min} to ts_{max})	150℃ 200℃ 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217℃ 60-150 seconds
Peak/Classification Temperature (Tp)	See Table 2
Time within 5℃ of actual Peak Temperature (tp)	20-3 0 seconds (WE-GF/WE-LAN: 10 s; Tp=245℃)
Ramp-Down Rate	6℃ / sec max.
Time 25℃ to Peak Temperature	8 minutes max.

Table 2 Package Classification Reflow Temperature

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 +0 °C *	260 +0 °C *	260 +0 °C *
1.6 mm - 2.5 mm	260 +0 °C *	250 +0 °C *	245 +0 °C *
≥2.5 mm	250 +0 °C *	245 +0 °C *	245 +0 °C *

refer to IPC/JEDEC J-STD-020D

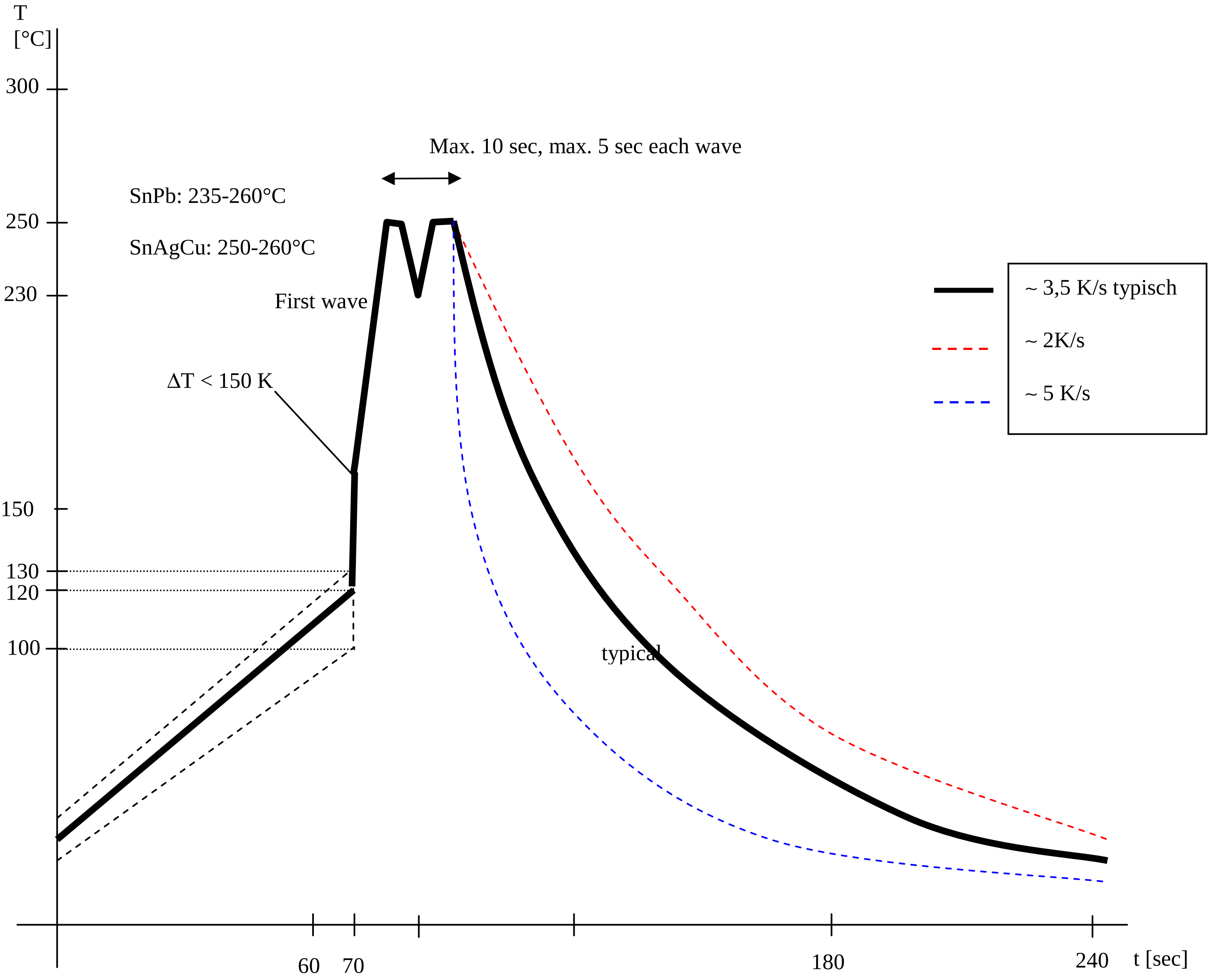
Note: All temperatures refer to topside of the package, measured on the package body surface

Recommended for all parts which are marked with the RoHS logo in the data sheet

Solder profile for wave soldering process

Figure 2 Classification wave soldering profile for THT components

refer to EN 61760-1:2006



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